



Product Change Notification: JPZA-04RAVO293

Date:

15-Jun-2026

Product Category:

Linear Comparators, Linear Op Amps

Notification Subject:

CCB 8304 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP6031T-E/OT, MCP65R41T-1202E/CHY, MCP65R46T-1202E/CHY, MCP65R41T-2402E/CHY, MCP65R46T-2402E/CHY, MCP6061T-E/OT, MCP6071T-E/OT and MCP6051T-E/OT catalog part numbers (CPN) available in 5L and 6L SOT-23 package at MTAI assembly site.

Affected CPNs:

[JPZA-04RAVO293_Affected_CPN_06152026.pdf](#)

[JPZA-04RAVO293_Affected_CPN_06152026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for MCP6031T-E/OT, MCP65R41T-1202E/CHY, MCP65R46T-1202E/CHY, MCP65R41T-2402E/CHY, MCP65R46T-2402E/CHY, MCP6061T-E/OT, MCP6071T-E/OT and MCP6051T-E/OT catalog part numbers (CPN) available in 5L and 6L SOT-23 package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site		Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material		Au	CuPdAu	Yes
Die Attach Material		8006NS (PFAS-Free)	8006NS (PFAS-Free)	No
Molding Compound Material		G600V	G600V	No
Lead-Frame Material*	5L SOT-23 Package	CDA194	CDA194	No
	6L SOT- 23 Package	C194	C194	No
DAP Surface Prep	5L SOT- 23 Package	Ag-RT	Ag-RT	No
	6L SOT- 23 Package	NiPdAu	NiPdAu	No
Lead-Frame Plating	5L SOT- 23 Package	Matte Tin	Matte Tin	No
	6L SOT- 23 Package	NiPdAu	NiPdAu	No

*Note: C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 14 September 2026 (date code: 2638)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	September 2026				
Work Week	23	24	25	26	27		36	37	38	39	40
Qual Report Availability			X								

Final PCN Issue Date			X								
Estimated Implementation Date									X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 15, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_JPZA-04RAV0293-Qualification-Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

MCP6031T-E/OT

MCP65R41T-1202E/CHY

MCP65R46T-1202E/CHY

MCP65R41T-2402E/CHY

MCP65R46T-2402E/CHY

MCP6061T-E/OT

MCP6071T-E/OT

MCP6051T-E/OT



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: JPZA-04RAVO293

Date:
June 15, 2026

Qualification of CuPdAu as a new wire material for MCP6031T-E/OT, MCP65R41T-1202E/CHY, MCP65R46T-1202E/CHY, MCP65R41T-2402E/CHY, MCP65R46T-2402E/CHY, MCP6061T-E/OT, MCP6071T-E/OT and MCP6051T-E/OT catalog part numbers (CPN) available in 5L and 6L SOT-23 package at MTAI assembly site. This is a Qualification by Similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of CuPdAu as a new wire material for MCP6031T-E/OT, MCP65R41T-1202E/CHY, MCP65R46T-1202E/CHY, MCP65R41T-2402E/CHY, MCP65R46T- 2402E/CHY, MCP6061T-E/OT, MCP6071T-E/OT and MCP6051T-E/OT catalog part numbers (CPN) available in 5L and 6L SOT-23 package at MTAI assembly site. This is a Qualification by Similarity (QBS).
CN	BC131408
QUAL ID	Q13103 (Rev. A)
MP CODE	GBCB4Y6AXB00
Part No.	MCP663T-E/CHY
Bonding No.	BDE-000371 Rev. A
CCB No.	1330.02 (Qual Date: November 21, 2013) and 8304
<u>Package</u>	
Type	6L SOT-23
<u>Lead Frame Paddle</u>	
size Material	Chip on Lead design
Surface	A194
Process	NiPdAu
Lead Lock	Etch
Part Number	No
<u>Die attach material</u>	10100604
Epoxy	
Wire	8006NS
Mold Compound	Au wire
Plating	G600V
Composition	NiPdAu



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI142303147	TMPE211517011.112	1336U 63
MTAI142303657	TMPE211517011.112	1336VJ7
MTAI142303664	TMPE211517011.112	1336VJK

Result

☒

Pass

☐

Fail

☐

6L SOT-23 assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD- 020D	135	0/135	Pass	

<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test :+25°C and 125°C System: ETS300	JESD22- A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 125°C System: ETS300			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H Inspection: External crack inspection all units under 40X Optical magnification Electrical Test: + 125°C System: ETS300	JESD22-A104	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: ETS300	JESD22-A118	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 6 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: ETS300	JESD22-A110	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB Electrical Test : +25°C and 125°C System: ETS300	JESD22-A103	45(0)	45 0/45	Pass	45 units

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of CuPdAu as a new wire material for MCP6031T-E/OT, MCP65R41T-1202E/CHY, MCP65R46T-1202E/CHY, MCP65R41T-2402E/CHY, MCP65R46T- 2402E/CHY, MCP6061T-E/OT, MCP6071T-E/OT and MCP6051T-E/OT catalog part numbers (CPN) available in 5L and 6L SOT-23 package at MTAI assembly site. This is a Qualification by Similarity (QBS).
CN	E000255869
QUAL ID	R2500021 (Rev. A)
MP CODE	A7BZ4YC8XF00
Part No.	MCP6293T-E/CH
Bonding No.	BD-002758 Rev. 01
CCB No.	7292 (Qual Date: February 28, 2025) and 8304
<u>Package</u>	
Type	6L SOT-23
<u>Lead Frame Paddle</u>	
size Material	72 x 41 mils
Surface	A194
Process	Ag single ring Plated
Lead Lock	Stamped
Part Number	No
Treatment	10100607
<u>Material</u>	BOT
Epoxy	
Wire	84-3J/8006NS
Mold Compound	CuPdAu wire
Plating	G600V
Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI253800952.000	TMPE223515732.143	24513US
MTAI253900664.000	TMPE223515732.143	24524CA
MTAI253900665.000	TMPE223515732.143	24524CP

Result

☒ Pass ☐ Fail ☐ _____

6L SOT-23 assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C and 125°C System: ETS300 Bake 150°C, 24 hrs. System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243	JESD22-A113 JIP/ IPC/JEDEC J-STD-020E	693(0)	0/693	Pass	Good Devices
	Electrical Test: +25°C and 125°C System: ETS300		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +125°C System: ETS300 Bond Strength: Wire Pull (>2.50 grams)	JESD22-A104	231(0)	231 0/231 0/15 0/15	Pass Pass Pass	Parts had been pre-conditioned at 260°C 77 units / lot
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: ETS300	JESD22-A118	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: ETS300	JESD22-A110	231(0)	231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C and 125°C System: ETS300		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC- Q100-001	30(0) Bonds	0/30	Pass	